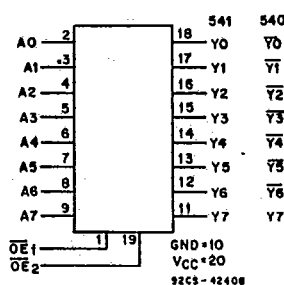


Technical Data

CD54/74AC540, CD54/74AC541
CD54/74ACT540, CD54/74ACT541

T-52-07



FUNCTIONAL DIAGRAM

Octal Buffer/Line Drivers, 3-State

CD74AC/ACT540 - Inverting

CD74AC/ACT541 - Non-Inverting

Type Features:

- Buffered inputs
- Typical propagation delay:
4.5 ns @ $V_{CC} = 5V$, $T_A = 25^\circ C$, $C_L = 50 pF$

The RCA-CD54/74AC540, -541 and CD54/74ACT540, -541 octal buffer/line drivers use the RCA ADVANCED CMOS technology. The CD54/74AC/ACT540 are inverting 3-state buffers having two active-LOW output enables. The CD54/74AC/ACT541 are non-inverting 3-state buffers having two active-LOW output enables.

The CD74AC540, -541 and CD74ACT540, -541 are supplied in 20-lead dual-in-line plastic packages (E suffix) and in 20-lead dual-in-line small-outline plastic packages (M suffix). Both package types are operable over the following temperature ranges: Commercial (0 to $70^\circ C$); Industrial (-40 to $+85^\circ C$); and Extended Industrial/Military (-55 to $+125^\circ C$).

The CD54AC540, -541 and CD54ACT540, -541, available in chip form (H suffix), are operable over the -55 to $+125^\circ C$ temperature range.

Family Features:

- Exceeds 2-kV ESD Protection - MIL-STD-883, Method 3015
- SCR-Latchup-resistant CMOS process and circuit design
- Speed of bipolar FAST®/AS/S with significantly reduced power consumption
- Balanced propagation delays
- AC types feature 1.5-V to 5.5-V operation and balanced noise immunity at 30% of the supply.
- ± 24 -mA output drive current
 - Fanout to 15 FAST® ICs
 - Drives 50-ohm transmission lines

*FAST is a Registered Trademark of Fairchild Semiconductor Corp.

TRUTH TABLE

CD54/74AC/ACT540		
INPUTS		OUTPUTS
OE1, OE2	A	Y
L	L	H
L	H	L
H	X	Z

TRUTH TABLE

CD54/74AC/ACT541		
INPUTS		OUTPUTS
OE1, OE2	A	Y
L	L	H
L	H	L
H	X	Z

H = High Voltage
 L = Low Voltage
 X = Immaterial
 Z = High Impedance

File Number 1857

T-52-07

CD54/74AC540, CD54/74AC541

CD54/74ACT540, CD54/74ACT541

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE (V_{CC})	-0.5 to 6 V
DC INPUT DIODE CURRENT, I_{IK} (for $V_i < -0.5$ V or $V_i > V_{CC} + 0.5$ V)	± 20 mA
DC OUTPUT DIODE CURRENT, I_{OK} (for $V_o < -0.5$ V or $V_o > V_{CC} + 0.5$ V)	± 50 mA
DC OUTPUT SOURCE OR SINK CURRENT per Output Pin, I_o (for $V_o > -0.5$ V or $V_o < V_{CC} + 0.5$ V)	± 50 mA
DC V_{CC} or GROUND CURRENT (I_{CC} or I_{GND})	± 100 mA*

POWER DISSIPATION PER PACKAGE (P_D):

For $T_A = -55$ to $+100^\circ\text{C}$ (PACKAGE TYPE E)	500 mW
For $T_A = +100$ to $+125^\circ\text{C}$ (PACKAGE TYPE E)	Derate Linearly at 8 mW/ $^\circ\text{C}$ to 300 mW
For $T_A = -55$ to $+70^\circ\text{C}$ (PACKAGE TYPE M)	400 mW
For $T_A = +70$ to $+125^\circ\text{C}$ (PACKAGE TYPE M)	Derate Linearly at 6 mW/ $^\circ\text{C}$ to 70 mW

OPERATING-TEMPERATURE RANGE (T_A)

OPERATING-TEMPERATURE RANGE (T_A)	-55 to $+125^\circ\text{C}$
STORAGE TEMPERATURE (T_{STG})	-65 to $+150^\circ\text{C}$

LEAD TEMPERATURE (DURING SOLDERING):

At distance $1/16 \pm 1/32$ in. (1.59 ± 0.79 mm) from case for 10 s maximum	$+265^\circ\text{C}$
Unit inserted into PC board min. thickness $1/16$ in. (1.59 mm) with solder contacting lead tips only	$+300^\circ\text{C}$

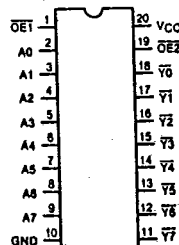
* For up to 4 outputs per device; add ± 25 mA for each additional output.**RECOMMENDED OPERATING CONDITIONS:**

For maximum reliability, normal operating conditions should be selected so that operation is always within the following ranges:

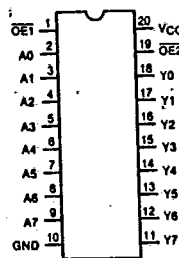
CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range, V_{CC} *: (For T_A = Full Package-Temperature Range) AC Types ACT Types	1.5	5.5	V
	4.5	5.5	V
DC Input or Output Voltage, V_i , V_o	0	V_{CC}	V
Operating Temperature, T_A	-55	+125	$^\circ\text{C}$
Input Rise and Fall Slew Rate, dV/dt at 1.5 V to 3 V (AC Types) at 3.6 V to 5.5 V (AC Types) at 4.5 V to 5.5 V (ACT Types)	0	50	ns/V
	0	20	ns/V
	0	10	ns/V
	0	10	ns/V

*Unless otherwise specified, all voltages are referenced to ground.

9

TERMINAL ASSIGNMENT DIAGRAMS

CD54/74AC/ACT540



CD54/74AC/ACT541

Technical Data

CD54/74AC540, CD54/74AC541
CD54/74ACT540, CD54/74ACT541

T-52-07

STATIC ELECTRICAL CHARACTERISTICS: AC Series

CHARACTERISTICS		TEST CONDITIONS		V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C						UNITS
					+25		-40 to +85		-55 to +125		
		V _I (V)	I _O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage	V _{IH}			1.5	1.2	—	1.2	—	1.2	—	V
				3	2.1	—	2.1	—	2.1	—	
				5.5	3.85	—	3.85	—	3.85	—	
Low-Level Input Voltage	V _{IL}			1.5	—	0.3	—	0.3	—	0.3	V
				3	—	0.9	—	0.9	—	0.9	
				5.5	—	1.65	—	1.65	—	1.65	
High-Level Output Voltage	V _{OH}	V _{IH} or V _{IL} #, *	-0.05	1.5	1.4	—	1.4	—	1.4	—	V
			-0.05	3	2.9	—	2.9	—	2.9	—	
			-0.05	4.5	4.4	—	4.4	—	4.4	—	
			-4	3	2.58	—	2.48	—	2.4	—	
			-24	4.5	3.94	—	3.8	—	3.7	—	
			-75	5.5	—	—	3.85	—	—	—	
			-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage	V _{OL}	V _{IH} or V _{IL} #, *	0.05	1.5	—	0.1	—	0.1	—	0.1	V
			0.05	3	—	0.1	—	0.1	—	0.1	
			0.05	4.5	—	0.1	—	0.1	—	0.1	
			12	3	—	0.36	—	0.44	—	0.5	
			24	4.5	—	0.36	—	0.44	—	0.5	
			75	5.5	—	—	—	1.65	—	—	
			50	5.5	—	—	—	—	—	1.65	
Input Leakage Current	I _I	V _{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current	I _{OZ}	V _{IH} or V _{IL} V _O = V _{CC} or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI	I _{CC}	V _{CC} or GND	0	5.5	—	8	—	80	—	160	μA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

* Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

Technical Data

CD54/74AC540, CD54/74AC541
CD54/74ACT540, CD54/74ACT541

STATIC ELECTRICAL CHARACTERISTICS: ACT Series

T-52-07

CHARACTERISTICS		TEST CONDITIONS		V_{CC} (V)	AMBIENT TEMPERATURE (T_A) - °C						UNITS
					+25		-40 to +85		-55 to +125		
		V_I (V)	I_O (mA)		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
High-Level Input Voltage	V_{IH}			4.5 to 5.5	2	—	2	—	2	—	V
Low-Level Input Voltage	V_{IL}			4.5 to 5.5	—	0.8	—	0.8	—	0.8	V
High-Level Output Voltage	V_{OH}	V_{IH} or V_{IL} #, *	-0.05	4.5	4.4	—	4.4	—	4.4	—	V
			-24	4.5	3.94	—	3.8	—	3.7	—	
			-75	5.5	—	—	3.85	—	—	—	
			-50	5.5	—	—	—	—	3.85	—	
Low-Level Output Voltage	V_{OL}	V_{IH} or V_{IL} #, *	0.05	4.5	—	0.1	—	0.1	—	0.1	V
			24	4.5	—	0.36	—	0.44	—	0.5	
			75	5.5	—	—	—	1.65	—	—	
			50	5.5	—	—	—	—	—	1.65	
Input Leakage Current	I_i	V_{CC} or GND		5.5	—	±0.1	—	±1	—	±1	μA
3-State Leakage Current	I_{OZ}	V_{IH} or V_{IL} $V_O = V_{CC}$ or GND		5.5	—	±0.5	—	±5	—	±10	μA
Quiescent Supply Current, MSI	I_{CC}	V_{CC} or GND	0	5.5	—	8	—	80	—	160	μA
Additional Quiescent Supply Current per Input Pin TTL Inputs High 1 Unit Load	ΔI_{CC}	$V_{CC}-2.1$		4.5 to 5.5	—	2.4	—	2.8	—	3	mA

#Test one output at a time for a 1-second maximum duration. Measurement is made by forcing current and measuring voltage to minimize power dissipation.

* Test verifies a minimum 50-ohm transmission-line-drive capability at +85°C, 75 ohms at +125°C.

ACT INPUT LOADING TABLE

INPUT	UNIT LOAD*	
	540	541
DATA	1.42	0.5
OE1, OE2	1.3	1.3

*Unit load is ΔI_{CC} limit specified in Static Characteristics Chart, e.g., 2.4 mA max. @ 25°C.

Technical Data

CD54/74AC540, CD54/74AC541
CD54/74ACT540, CD54/74ACT541

T-52-07

SWITCHING CHARACTERISTICS: AC Series; $t_r, t_f = 3 \text{ ns}$, $C_L = 50 \text{ pF}$

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Output AC540	t _{PLH} t _{PHL}	1.5 3.3* 5†	— 2.4 1.8	77 8.6 6.2	— 2.4 1.7	85 9.5 6.8	ns
AC541	t _{PLH} t _{PHL}	1.5 3.3 5	— 2.8 2.1	89 9.9 7.1	— 2.7 2	98 10.9 7.8	ns
Enable, to Output to Output	t _{PZL} t _{PZH}	1.5 3.3 5	— 4.6 3.1	136 16.4 10.9	— 4.5 3	150 18 12	ns
Disable to Output to Output	t _{PLZ} t _{PHZ}	1.5 3.3 5	— 3.9 3.1	136 13.6 10.9	— 3.8 3	150 15 12	ns
Power Dissipation Capacitance AC540 AC541	C _{PD} ‡	— —	60 Typ. 60 Typ.		60 Typ. 60 Typ.		pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _i	—	—	10	—	10	pF.
3-State Output Capacitance	C _o	—	—	15	—	15	pF

SWITCHING CHARACTERISTICS: ACT Series; $t_r, t_f = 3 \text{ ns}$, $C_L = 50 \text{ pF}$

CHARACTERISTICS	SYMBOL	V _{CC} (V)	AMBIENT TEMPERATURE (T _A) - °C				UNITS
			-40 to +85		-55 to +125		
			MIN.	MAX.	MIN.	MAX.	
Propagation Delays: Data to Output ACT540	t _{PLH} t _{PHL}	5†	1.9	6.5	1.8	7.2	ns
ACT541	t _{PLH} t _{PHL}	5†	2.1	7.5	2.1	8.2	ns
Enable to Output	t _{PZL} t _{PZH}	5	3.5	12.2	3.4	13.4	ns
Disable to Output	t _{PLZ} t _{PHZ}	5	3.5	12.2	3.4	13.4	
Power Dissipation Capacitance ACT540 ACT541	C _{PD} §	— —	60 Typ. 60 Typ.		60 Typ. 60 Typ.		pF
Min. (Valley) V _{OH} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OHV} See Fig. 1	5	4 Typ. @ 25°C				V
Max. (Peak) V _{OL} During Switching of Other Outputs (Output Under Test Not Switching)	V _{OLP} See Fig. 1	5	1 Typ. @ 25°C				V
Input Capacitance	C _I	—	—	10	—	10	pF
3-State Output Capacitance	C _O	—	—	15	—	15	pF

*3.3 V: min. is @ 3.6 V
max. is @ 3 V

†5 V: min. is @ 5.5 V
max. is @ 4.5 V

§ C_{PD} is used to determine the dynamic power consumption, per channel.

For AC series, $P_D = V_{CC}^2 f_i (C_{PD} + C_L)$

For ACT series, $P_D = V_{CC}^2 f_i (C_{PD} + C_L) + V_{CC} \Delta I_{CC}$ where

f_i = input frequency

C_L = output load capacitance

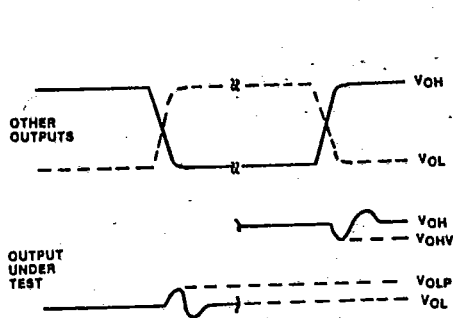
V_{CC} = supply voltage.

CD54/74AC540, CD54/74AC541

CD54/74ACT540, CD54/74ACT541

T-52-07

PARAMETER MEASUREMENT INFORMATION



NOTES:

1. V_{OHV} and V_{OLP} ARE MEASURED WITH RESPECT TO A GROUND REFERENCE NEAR THE OUTPUT UNDER TEST.
2. INPUT PULSES HAVE THE FOLLOWING CHARACTERISTICS:
 $PRR \leq 1 \text{ MHz}$, $t_r = 3 \text{ ns}$, $t_f = 3 \text{ ns}$, SKEW 1 ns .
3. R.F. FIXTURE WITH 700-MHz DESIGN RULES REQUIRED. IC SHOULD BE SOLDERED INTO TEST BOARD AND BYPASSED WITH $0.1 \mu\text{F}$ CAPACITOR. SCOPE AND PROBES REQUIRE 700-MHz BANDWIDTH.

92CS-42405

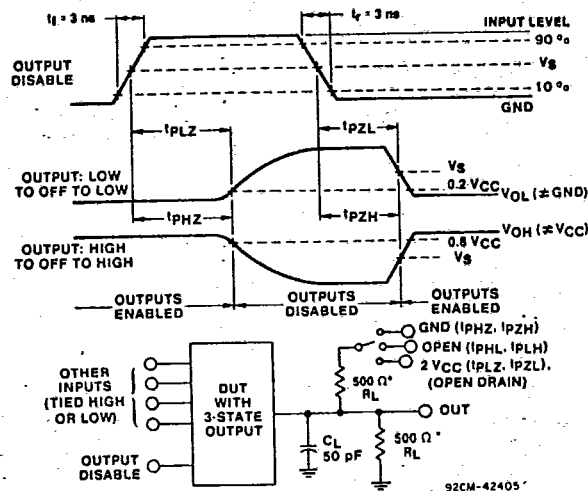
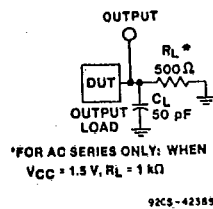
*FOR AC SERIES ONLY: WHEN $V_{CC} = 1.5 \text{ V}$, $R_L = 1 \text{ k}\Omega$

Fig. 1 - Simultaneous switching transient waveforms.

Fig. 2 - Three-state propagation delay waveforms and test circuit.

*FOR AC SERIES ONLY: WHEN $V_{CC} = 1.5 \text{ V}$, $R_L = 1 \text{ k}\Omega$

92CS-42389

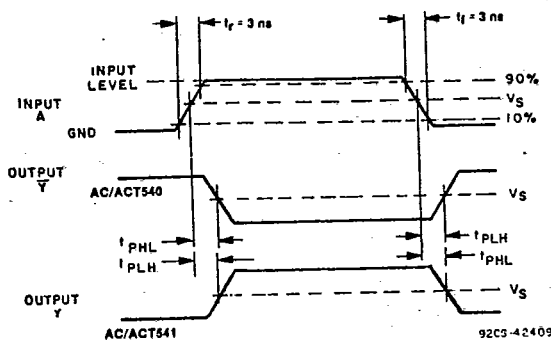
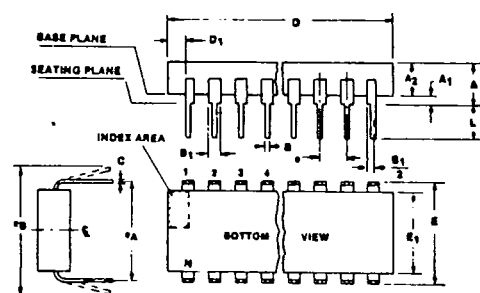


Fig. 3 - Propagation delay times and test circuit.

	CD54/74AC	CD54/74ACT
Input Level	V_{CC}	3 V
Input Switching Voltage, V_S	$0.5 V_{CC}$	1.5 V
Output Switching Voltage, V_S	$0.5 V_{CC}$	$0.5 V_{CC}$

Dual-In-Line Plastic Packages

T-90-20

(E) Suffix (JEDEC MS-001-AC)
14-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	0.725	0.795	18.42	20.19	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	14		14		11

92CS-39901

(E) Suffix (JEDEC MS-001-AA)
16-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	0.745	0.840	18.93	21.33	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	16		16		11

92CS-39900

Notes:

1. Refer to JEDEC Publication No. 95 JEDEC Registered and Standard Outlines for Solid State Products, for rules and general information concerning registered and standard outlines, in Section 2.2.
2. Protrusions (flash) on the base plane surface shall not exceed 0.010 in. (0.25 mm).
3. The dimension shown is for full leads. "Half" leads are optional at lead positions

$$1, N, \frac{N}{2}, \frac{N}{2} + 1.$$
4. Dimension D does not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 in. (0.25 mm).
5. E is the dimension to the outside of the leads and is measured with the leads perpendicular to the base plane (zero lead spread).
6. Dimension E₁ does not include mold flash or protrusions.
7. Package body and leads shall be symmetrical around center line shown in end view.
8. Lead spacing e shall be non-cumulative and shall be measured at the lead lip. This measurement shall be made before insertion into gauges, boards or sockets.
9. This is a basic installed dimension. Measurement shall be made with the device installed in the seating plane gauge (JEDEC Outline No. GS-3, seating plane gauge). Leads shall be in true position within 0.010 in. (0.25 mm) diameter for dimension e_A.
10. e_B is the dimension to the outside of the leads and is measured at the lead tips before the device is installed. Negative lead spread is not permitted.
11. N is the maximum number of lead positions.
12. Dimension D₁ at the left end of the package must equal dimension D₁ at the right end of the package within 0.030 in. (0.76 mm).
13. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.

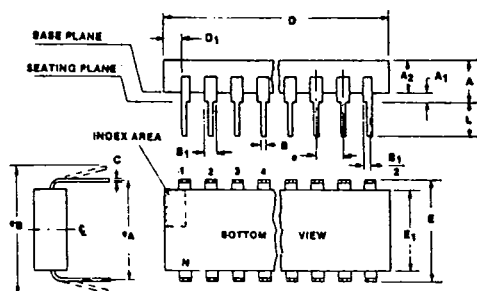
(E) Suffix (JEDEC MS-001-AE)
20-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	0.925	1.060	23.5	26.9	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	20		20		11

92CS-39997

Dual-In-Line Plastic Packages

T-90-20

(E) Suffix (JEDEC MS-001-AF)
24-Lead Dual-In-Line Plastic Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	—	0.210	—	5.33	9
A ₁	0.015	—	0.39	—	9
A ₂	0.115	0.195	2.93	4.95	
B	0.014	0.022	0.356	0.558	
B ₁	0.045	0.070	1.15	1.77	3
C	0.008	0.015	0.204	0.381	
D	1.125	1.275	28.6	32.3	4
D ₁	0.005	—	0.13	—	12
E	0.300	0.325	7.62	8.25	5
E ₁	0.240	0.280	6.10	7.11	6, 7
e	0.100 BSC		2.54 BSC		8
e _A	0.300 BSC		7.62 BSC		9
e _B	—	0.430	—	10.92	10
L	0.115	0.160	2.93	4.06	9
N	24		24		11

92CS-39943

Notes:

1. Refer to JEDEC Publication No. 95 JEDEC Registered and Standard Outlines for Solid State Products, for rules and general information concerning registered and standard outlines, in Section 2.2.
2. Protrusions (flash) on the base plane surface shall not exceed 0.010 in. (0.25 mm).
3. The dimension shown is for full leads. "Half" leads are optional at lead positions

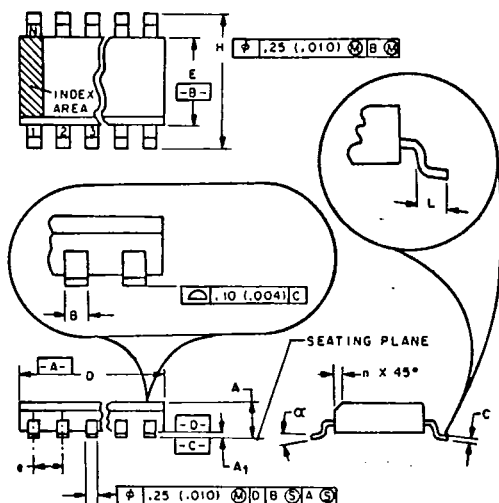
$$1, N, \frac{N}{2}, \frac{N}{2} + 1.$$
4. Dimension D does not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.010 in. (0.25 mm).
5. E is the dimension to the outside of the leads and is measured with the leads perpendicular to the base plane (zero lead spread).
6. Dimension E₁ does not include mold flash or protrusions.
7. Package body and leads shall be symmetrical around

center line shown in end view.

8. Lead spacing e shall be non-cumulative and shall be measured at the lead tip. This measurement shall be made before insertion into gauges, boards or sockets.
9. This is a basic installed dimension. Measurement shall be made with the device installed in the seating plane gauge (JEDEC Outline No. GS-3, seating plane gauge). Leads shall be in true position within 0.010 in. (0.25 mm) diameter for dimension e_A.
10. e_B is the dimension to the outside of the leads and is measured at the lead tips before the device is installed. Negative lead spread is not permitted.
11. N is the maximum number of lead positions.
12. Dimension D₁ at the left end of the package must equal dimension D₁ at the right end of the package within 0.030 in. (0.76 mm).
13. For automatic insertion, any raised irregularity on the top surface (step, mesa, etc.) shall be symmetrical about the lateral and longitudinal package centerlines.

13

Dual-In-Line Small-Outline Plastic Packages



NOTES:

1. Refer to applicable symbol list.
2. Dimensioning and tolerancing per ANSI Y14.5M-1982.
3. "D" is a reference datum.
4. "A" and "B" are reference datums and do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm (0.006 in.).
5. The chamfer on the body is optional. If it is not present, a visual index feature must be located within the cross-hatched area.
6. "L" is the length of terminal for soldering to a substrate.
7. "N" is the number of terminal positions.
8. Terminal numbers are shown for reference only.
9. Controlling dimensions: MILLIMETERS.

T-90-20

M Suffix (JEDEC MS-012AB)

14-Lead Dual-In-Line Small-Outline (SO) Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.0532	0.0688	1.35	1.75	
A ₁	0.0040	0.0098	0.10	0.25	
B	0.0138	0.020	0.35	0.508	
C	0.0075	0.0098	0.19	0.25	
D	0.3367	0.3444	8.55	8.75	4
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		
H	0.2284	0.2440	5.80	6.20	
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	14		14		7
α	0°	8°	0°	8°	

Notes: 1, 2, 3, 8, 9

92CS-38924R2

M Suffix (JEDEC MS-012AC)

16-Lead Dual-In-Line Small-Outline (SO) Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.0532	0.0688	1.35	1.75	
A ₁	0.0040	0.0098	0.10	0.25	
B	0.0138	0.020	0.35	0.508	
C	0.0075	0.0098	0.19	0.25	
D	0.3859	0.3937	9.80	10.00	4
E	0.1497	0.1574	3.80	4.00	4
e	0.050 BSC		1.27 BSC		
H	0.2284	0.2440	5.80	6.20	
h	0.0099	0.0196	0.25	0.50	5
L	0.016	0.050	0.40	1.27	6
N	16		16		7
α	0°	8°	0°	8°	

Notes: 1, 2, 3, 8, 9

92CS-38925R2

M Suffix (JEDEC MS-013AC)

20-Lead Dual-In-Line Small-Outline (SO) Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.0926	0.1043	2.35	2.65	
A ₁	0.0040	0.0118	0.10	0.30	
B	0.0138	0.020	0.35	0.508	
C	0.0091	0.0125	0.23	0.32	
D	0.4861	0.5118	12.60	13.00	4
E	0.2914	0.2992	7.40	7.60	4
e	0.050 BSC		1.27 BSC		
H	0.394	0.419	10.00	10.65	
h	0.010	0.029	0.25	0.75	5
L	0.016	0.050	0.40	1.27	6
N	20		20		7
α	0°	8°	0°	8°	

Notes: 1, 2, 3, 8, 9

92CS-38926R2

M Suffix (JEDEC MS-013AD)

24-Lead Dual-In-Line Small-Outline (SO) Package

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.0926	0.1043	2.35	2.65	
A ₁	0.0040	0.0118	0.10	0.30	
B	0.0138	0.020	0.35	0.508	
C	0.0091	0.0125	0.23	0.32	
D	0.5985	0.6141	15.20	15.60	4
E	0.2914	0.2992	7.40	7.60	4
e	0.050 BSC		1.27 BSC		
H	0.394	0.419	10.00	10.65	
h	0.010	0.029	0.25	0.75	5
L	0.016	0.050	0.40	1.27	6
N	24		24		7
α	0°	8°	0°	8°	

Notes: 1, 2, 3, 8, 9

92CS-39037R2